CLAIMS

1. A system, comprising:

a cavity defined by conductive walls;

a printed circuit board (PCB) within the cavity;

a first ground plane layer under the PCB; and

shorting posts extending into the cavity from the first ground plane layer and configured to suppress higher order electromagnetic modes generated by operation of the PCB, wherein:

the shorting posts form at least one edge wall about a perimeter of a unit cell of the PCB;

at least one of the at least one edge wall includes two wall segments separated by a gap;

the shorting posts of each wall segment are spaced apart by a first distance;

shorting posts are not located in the gap;

a pair of the shorting posts adjacent the gap, one shorting post from each of the wall segments, are spaced apart by a second distance; and

the second distance is greater than the first distance.

2. The system according to claim 1, further including a second ground plane layer over the PCB, wherein the conductive walls and the first and second ground plane layers surround the PCB.

3. The system according to claim 1, wherein the shorting posts comprise solder reflow components.

4. The system according to claim 1, wherein the shorting posts comprise a series of ball stacks generated from a wire using wire bond equipment.

5. The system according to claim 1, further including a shorting post proximate a center of the unit cell.

6. The system according to claim 1, further including integrated circuits (ICs) on the PCB, wherein at least some of the shorting posts provide a generally circular formation about at least some of the ICs in the cavity.

7. The system according to claim 6, wherein at least some of the shorting posts are located inside the generally circular formation configured to reduce coupling between different unit cells of the PCB.